

SLANTED VIAS FOR ELECTRICAL CIRCUITS ON CIRCUIT BOARDS AND
OTHER SUBSTRATES

ABSTRACT OF THE DISCLOSURE

Circuit boards, microelectronic devices, and other apparatuses having slanted vias are disclosed herein. In one embodiment, an apparatus for interconnecting electronic components includes a dielectric portion having a first surface and a second surface. A first terminal is disposed on the first surface of the dielectric portion for connection to a first electronic component. A second terminal is disposed on the second surface of the dielectric portion for connection to a second electronic component. The apparatus further includes a passage extending through the dielectric portion along a longitudinal axis oriented at an oblique angle relative to the first surface. The passage is at least partially filled with conductive material electrically connecting the first terminal to the second terminal.

Figure: 3